

High-Current, Low-Dropout, 1.1 to 5 V Regulator

Features and Benefits

- 3 A Output Current
- 0.7 V Maximum Dropout Voltage at $I_0 = 3 A$
- 1 µA Maximum Standby Current
- Adjustable 1.1 to 5 V Output Voltage
- Remote Voltage Sensing
- Foldback Current Limiting
- Thermal Protection

Applications

- TVs, VCRs, Electronic Games
- Embedded Core, Memory, or Logic Supplies
- Printers and Other Office Equipment
- Industrial Machinery
- Secondary-Side Stabilization of Multi-Output SMPS

HotRet

Package: 5-pin TO-220

Not to scale

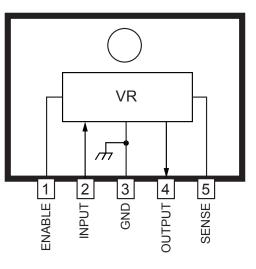
Description

Designed to meet the high-current requirements in industrial and consumer applications; embedded core, memory, or logic supplies; TVs, VCRs, and office equipment, the SI-3011ZF voltage regulator offers the reduced dropout voltage and low quiescent current essential for improved efficiency. This device delivers a regulated output at up to 3 A. Integrated thermal and overcurrent protection enhance overall system reliability. Devices with fixed output voltages of 2.5 V or 3.3 V are also available.

Quiescent current does not increase significantly as the dropout voltage is approached, an ideal feature in standby/resume power systems where data integrity is crucial. Regulator accuracy and excellent temperature characteristics are provided by a bandgap reference. An LS-TTL/CMOS-compatible input gives the designer complete control over power up, standby, or power down. A pnp pass element provides a dropout voltage of less than 700 mV at 3 A of load current. Low output voltages eliminate the need for expensive PWM buck converters. The low dropout voltage permits more efficient regulation before output regulation is lost.

This device is supplied in a fully molded TO-220-style 5-lead flange-mounted, high power, isolated plastic package. A similar device in a lower-power surface-mount plastic package is the SI-3011ZD.

Pin-Out Diagram



Selection Guide

Part Number

SI-3011ZF

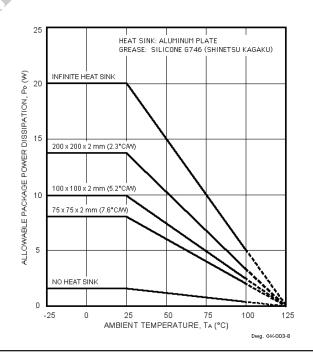
Absolute Maximum Ratings

For the availability of parts meeting –40°C requirements, contact a Sanken Sales Representative.					
Absolute Maximum Ratings					
Characteristic	Symbol	Notes	Rating	Units	
Input Voltage	VI		10	V	
Output Current	Io	Output current rating is limited by input voltage, duty cycle, and ambient temperature. Under any set of conditions, do not exceed a junction temperature of +125°C.	3	A	
Enable Input Voltage	VE			V	
Junction Temperature	TJ	125		°C	
Storage Temperature	T _{stg}	-4		°C	

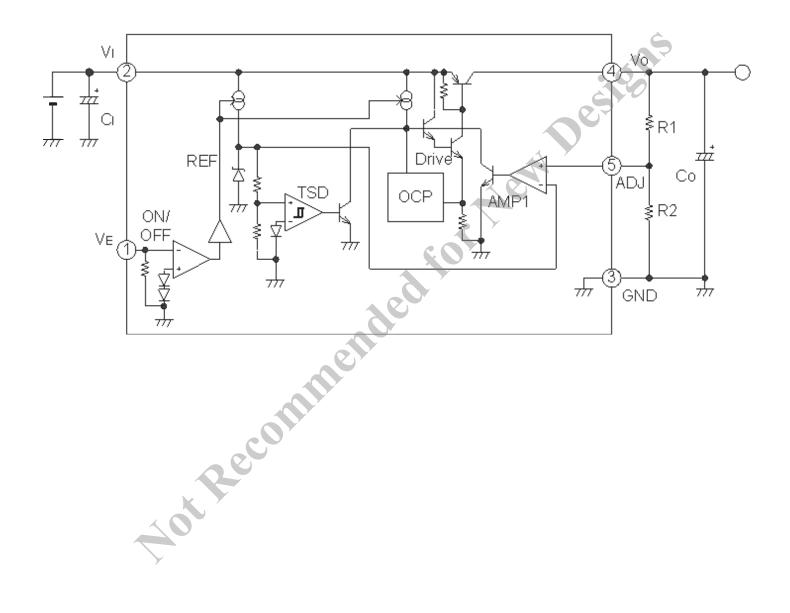
Recommended Operating Conditions

Characteristic	Symbol	Conditions	Min.	Max.	Unit
DC Input Voltage	VI		-	6	V
DC Output Current	Io		0	3	А
Adjustable Voltage Range	V _{ADJ}		1.2	5	V
Operating Junction Temperature	TJ		-20	100	°C
	com	25 I I I I HEAT SINK: ALUMINUM PLATE GREASE: SILICONE G746 (SHINETSU KAGAKU)			





Functional Block Diagram

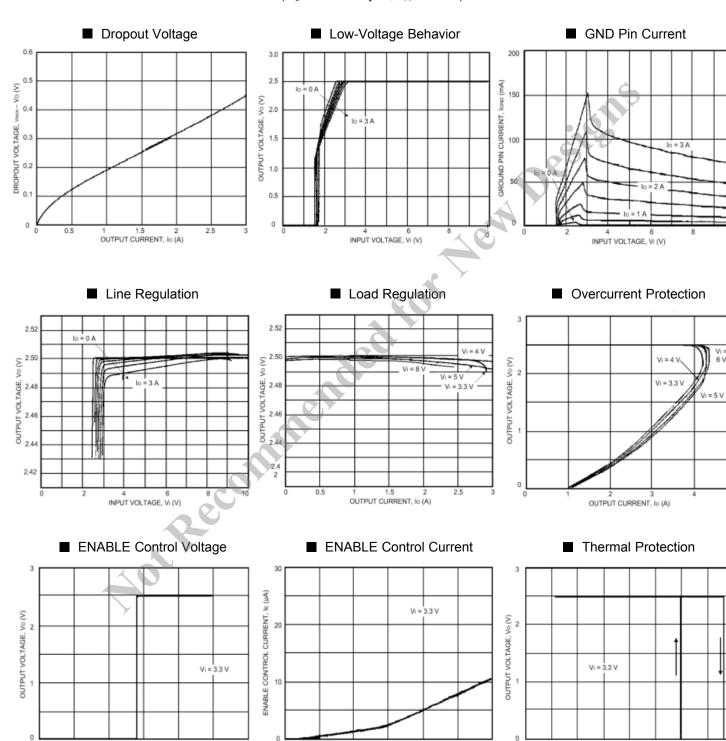


ELECTRICAL CHARACTERISTICS at $T_A = 25^{\circ}$ C, $V_O = 2.5$ V adjusted, $V_E = 2$ V, unless otherwise noted

Characteristics	Symbol	Test Conditions	Min.	Typ.1	Max.	Unit
Output Voltage	Vo	$V_{I} = V_{O(nom)} + 1 V, I_{O} = 10 mA$	_	V _{O(nom)}	_	V
	V _{O(off)}	V _E = 0 V	_	—	0.5	V
Output Voltage Temperature Coefficient	a _{vo}	$0^{\circ}C \leq T_{J} \leq 100^{\circ}C$	-	±0.3		mV/°C
Internal Reference Voltage	V _{ref}	$V_{I} = V_{O(nom)} + 1 V, I_{O} = 10 mA$	1.078	1.100	1.122	V
Output Short-Circuit Current ²	I _{OM}	V _I = V _{O(nom)} + 1 V	3.2	-0	_	А
Line Regulation	$\Delta V_{O(\Delta VI)}$	V_{I} = 3.0 to 5.0 V, I_{O} = 10 mA	-	? -	10	mV
Load Regulation	$\Delta V_{O(\Delta IO)}$	$V_1 = 3.3 \text{ V}, I_0 = 0 \text{ to } 3.0 \text{ A}$		_	40	mV
Dropout Voltage	V _I (min) – V _O	I _O = 3.0 A	-	-	0.7	V
Ground Terminal Current	I _{GND}	$V_{I} = V_{O(nom)} + 1 V, I_{O} = 0 mA, V_{E} = 2.0 V$	-	1.0	1.5	mA
		$V_{I} = V_{O(nom)} + 1 V, V_{E} = 0 V$	_	_	1.0	μA
Enable Input Voltage	V _{EH}	Output on	2.0	_	_	V
	V _{EL}	Output off	-	_	0.8	V
Enable Input Current	I _{EH}	$V_{\rm E} = 2.7 {\rm V}$	_	-	100	μA
	I _{EL}	V _E = 0 V	_	0	-5.0	μA
Ripple Rejection Ratio	PSRR	V_{I} = $V_{O(nom)}$ + 1 V, 100 Hz \leq f \leq 120 Hz	_	60	-	dB
Thermal Shutdown	TJ		135	152	_	°C

¹Typical values are given for circuit design information only. ²Output short-circuit current is at the point where output voltage has decreased 5% below V_{O(nom)}.

Aot Recommin



Typical Characteristics $(V_{O} = 2.5 \text{ V adjust}, T_{A} = 25^{\circ}\text{C})$

0.5

1.5

ENABLE CONTROL VOLTAGE, VE (V)

2.5

3

0

0.5

1.5

ENABLE CONTROL VOLTAGE, VE (A)

140 160

20

2.5

3

2

60 80 100 120

JUNCTION TEMPERATURE, TJ (°C)

Vi = 6 V

Input Capacitor (C_I , approximately 10 μ F). This is necessary either when the input line includes inductance or when the wiring is long.

Output Capacitor (C_O , > 47 μ F). This device is not designed for a use with a very low ESR output capacitor such as a ceramic capacitor. Output oscillation may occur with that kind of capacitor.

Output Voltage Adjustable Resistors (R1 and R2). The output voltage is adjusted by R1 and R2. $10 \text{ k}\Omega$ or

11 k Ω for R2 is recommended.

 $R1 = (V_O - V_{ref}) / (V_{ref} / R2)$

For an output voltage of 1.8 V or less, add a 10 k Ω resistor between ADJ and the junction of R1 and R2.

Determination of DC Input Voltage. The minimum input voltage $V_I(min)$ should be higher than the sum of the fixed output voltage and the maximum rated dropout voltage. If setting the output voltage lower than 2.0 V, the minimum input voltage should be more than 2.4 V.

Overcurrent Protection. The SI-3000ZD series has a built-in fold-back type overcurrent protection circuit, which limits the output current at a start-up mode. It thus cannot be used in applications that require current at the start-up mode such as:

(1) constant-current load,

(2) power supply with positive and negative outputs to common load (a center-tap type power supply), or

(3) raising the output voltage by putting a diode or a resistor between the device ground and system ground.

Thermal Protection. Circuitry turns off the pass transistor when the junction temperature rises above 135°C. It is intended only to protect the device from failures due to excessive junction temperatures and should not imply that output short circuits or continuous overloads are permitted.

Heat Radiation and Reliability. The reliability of the IC is directly related to the junction temperature (T_J) in its operation. Accordingly, careful consideration should be given to heat dissipation. The graph on page 2 illustrates the effect of thermal resistance on the allowable package power dissipation.

The junction temperature (T_J) can be determined from either of the following equations:

 $T_{\rm J} = (P_{\rm D} \times R_{\rm \theta JA}) +$

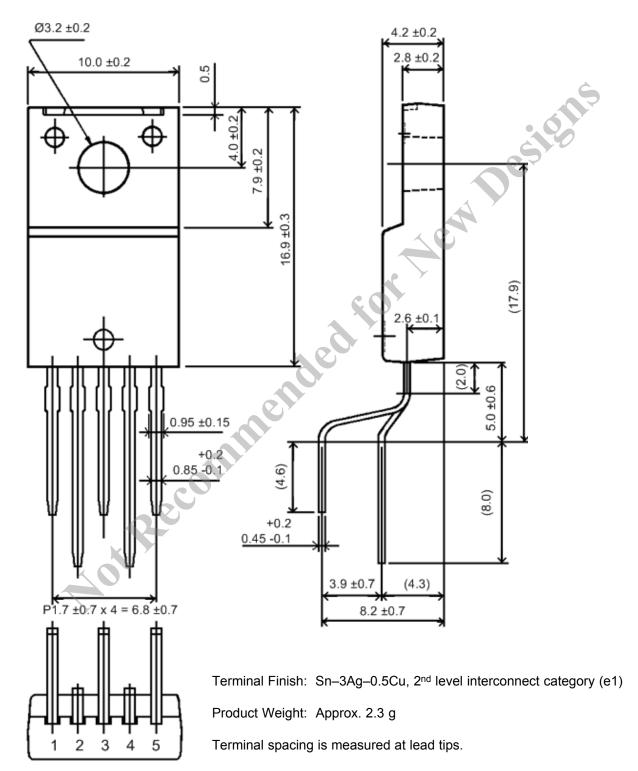
 $T_{\rm J} = (P_{\rm D} \times R_{\rm \theta JC}) +$

or

where $P_D = I_O \times (V_I - V_O)$ and $R_{\theta JC} = 5 \text{ °C/W}.$

Parallel Operation. Parallel operation to increase load current is not permitted.





SI-3011ZF

Because reliability can be affected adversely by improper storage environments and handling methods, please observe the following cautions.

Cautions for Storage

- Ensure that storage conditions comply with the standard temperature (5°C to 35°C) and the standard relative humidity (around 40% to 75%); avoid storage locations that experience extreme changes in temperature or humidity.
- Avoid locations where dust or harmful gases are present and avoid direct sunlight.
- Reinspect for rust on leads and solderability of the products that have been stored for a long time.

Cautions for Testing and Handling

- When tests are carried out during inspection testing and other standard test periods, protect the product from power surges from the testing device, shorts between adjacent product packages, and shorts to the heatsink.
- The screwing torque for attaching a heatsink shall be 58.8 to 68.6 N•cm (6.0 to 7.0 kgf•cm).
- Ensure there are no foreign objects between the heatsink and thermal pad; only silicone thermal grease is allowed.

Remarks About Using Silicone Grease with a Heatsink

- When silicone grease is used in mounting this product with a heatsink, grease shall be applied evenly and thinly. If more silicone grease than required is applied, it may produce stress.
- Volatile-type silicone greases may permeate the product and produce cracks after long periods of time, resulting in reduced heat radiation effect, and possibly shortening the lifetime of the product.
- Hard silicone greases may cause cracks in the product when screwing the product to a heatsink.

• Our recommended silicone greases for heat radiation purposes, which will not cause any adverse effect on the product life, are indicated below:

	Туре	Suppliers
	G746	Shin-Etsu Chemical Co., Ltd.
	YG6260	Momentive Performance Materials LLC
	SC102	Dow Corning Toray Co., Ltd.
Sold	ering	

- When soldering the products, please be sure to minimize the working time, within the following limits:
 260±5°C 10 s
 380±5°C 5 s
- Soldering should be at a distance of at least 1.5 mm from the body of the product.

Electrostatic Discharge

- When handling the products, the operator must be grounded. Grounded wrist straps worn should have at least 1 M Ω of resistance from the operator to ground to prevent shock hazard, and it should be placed near the operator.
- Workbenches where the products are handled should be grounded and be provided with conductive table and floor mats.
- When using measuring equipment such as a curve tracer, the equipment should be grounded.
- When soldering the products, the head of soldering irons or the solder bath must be grounded in order to prevent leak voltages generated by them from being applied to the product.
- The product should always be stored and transported in Sanken shipping containers or conductive containers, or be wrapped in aluminum foil.

- The contents in this document are subject to changes, for improvement and other purposes, without notice. Make sure that this is the latest revision of the document before use.
- Application and operation examples described in this document are quoted for the sole purpose of reference for the use of the products herein and Sanken can assume no responsibility for any infringement of industrial property rights, intellectual property rights or any other rights of Sanken or any third party which may result from its use.
- Although Sanken undertakes to enhance the quality and reliability of its products, the occurrence of failure and defect of semiconductor products at a certain rate is inevitable. Users of Sanken products are requested to take, at their own risk, preventative measures including safety design of the equipment or systems against any possible injury, death, fires or damages to the society due to device failure or malfunction.
- Sanken products listed in this document are designed and intended for the use as components in general purpose electronic equipment or apparatus (home appliances, office equipment, telecommunication equipment, measuring equipment, etc.).

When considering the use of Sanken products in the applications where higher reliability is required (transportation equipment and its control systems, traffic signal control systems or equipment, fire/crime alarm systems, various safety devices, etc.), and whenever long life expectancy is required even in general purpose electronic equipment or apparatus, please contact your nearest Sanken sales representative to discuss, prior to the use of the products herein.

The use of Sanken products without the written consent of Sanken in the applications where extremely high reliability is required (aerospace equipment, nuclear power control systems, life support systems, etc.) is strictly prohibited.

• In the case that you use Sanken products or design your products by using Sanken products, the reliability largely depends on the degree of derating to be made to the rated values. Derating may be interpreted as a case that an operation range is set by derating the load from each rated value or surge voltage or noise is considered for derating in order to assure or improve the reliability. In general, derating factors include electric stresses such as electric voltage, electric current, electric power etc., environmental stresses such as ambient temperature, humidity etc. and thermal stress caused due to self-heating of semiconductor products. For these stresses, instantaneous values, maximum values and minimum values must be taken into consideration.

In addition, it should be noted that since power devices or IC's including power devices have large self-heating value, the degree of derating of junction temperature affects the reliability significantly.

- When using the products specified herein by either (i) combining other products or materials therewith or (ii) physically, chemically or otherwise processing or treating the products, please duly consider all possible risks that may result from all such uses in advance and proceed therewith at your own responsibility.
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